

**IGBT Module U-Series 1200V / 75A 6 in one-package****■ Features**

- High speed switching
- Voltage drive
- Low inductance module structure

**■ Applications**

- Inverter for Motor drive
- AC and DC Servo drive amplifier
- Uninterruptible power supply
- Industrial machines, such as Welding machines

**■ Maximum ratings and characteristics****● Absolute maximum ratings (at Tc=25°C unless otherwise specified)**

Item	Symbol	Conditions	Rating	Unit	
Collector-Emitter voltage	V <sub>CES</sub>		1200	V	
Gate-Emitter voltage	V <sub>GES</sub>		±20	V	
Collector current	I <sub>c</sub>	Continuous	T <sub>c</sub> =25°C	100	A
			T <sub>c</sub> =80°C	75	
	I <sub>cp</sub>	1ms	T <sub>c</sub> =25°C	200	
			T <sub>c</sub> =80°C	150	
	-I <sub>c</sub>			75	
-I <sub>c</sub> pulse			150		
Collector Power Dissipation	P <sub>c</sub>	1 device	390	W	
Junction temperature	T <sub>j</sub>		+150	°C	
Storage temperature	T <sub>stg</sub>		-40 to +125		
Isolation voltage	between terminal and copper base *1	V <sub>iso</sub>	AC:1min.	2500	VAC
	between thermistor and others *2				
Screw Torque	Mounting *3	-	3.5	N·m	

\*1: All terminals should be connected together when isolation test will be done.

\*2: Two thermistor terminals should be connected together, each other terminals should be connected together and shorted to base plate when isolation test will be done.

\*3: Recommendable value : 2.5 to 3.5 N·m(M5)

**● Electrical characteristics (at T<sub>j</sub>=25°C unless otherwise specified)**

Item	Symbols	Conditions	Characteristics			Unit		
			Min.	Typ.	Max.			
Inverter	Zero gate voltage collector current	I <sub>CES</sub>	V <sub>GE</sub> =0V, V <sub>CES</sub> =1200V		-	-	1.0	mA
	Gate-Emitter leakage current	I <sub>GES</sub>	V <sub>CES</sub> =0V, V <sub>GE</sub> =±20V		-	-	200	nA
	Gate-Emitter threshold voltage	V <sub>GE(th)</sub>	V <sub>CES</sub> =20V, I <sub>C</sub> =75mA		4.5	6.5	8.5	V
	Collector-Emitter saturation voltage	V <sub>CES(sat)</sub> (terminal)	V <sub>GE</sub> =15V, I <sub>C</sub> =75A	T <sub>j</sub> =25°C	-	2.05	2.40	V
				T <sub>j</sub> =125°C	-	2.30	-	
		V <sub>CES(sat)</sub> (chip)		T <sub>j</sub> =25°C	-	1.75	2.10	
				T <sub>j</sub> =125°C	-	2.00	-	
	Input capacitance	C <sub>ies</sub>	V <sub>CES</sub> =10V, V <sub>GE</sub> =0V, f=1MHz		-	8	-	nF
	Turn-on time	t <sub>on</sub>	V <sub>CC</sub> =600V		-	0.25	1.20	μs
		t <sub>r</sub>	I <sub>C</sub> =75A		-	0.12	0.60	
		t <sub>r(i)</sub>	V <sub>GE</sub> =±15V		-	0.03	-	
	Turn-off time	t <sub>off</sub>	R <sub>G</sub> =9.1 Ω		-	0.36	1.00	μs
		t <sub>f</sub>			-	0.07	0.30	
	Forward on voltage	V <sub>F</sub> (terminal)	V <sub>GE</sub> =0V I <sub>F</sub> =75A	T <sub>j</sub> =25°C	-	2.10	2.50	V
				T <sub>j</sub> =125°C	-	2.30	-	
V <sub>F</sub> (chip)		T <sub>j</sub> =25°C		-	1.80	2.20		
		T <sub>j</sub> =125°C		-	2.00	-		
Reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> =75A		-	-	0.35	μs	
Lead resistance, terminal-chip*4	R <sub>lead</sub>			-	4.1	-	mΩ	
Thermistor	Resistance	R	T=25°C	-	5000	-	Ω	
			T=100°C	465	495	520		
	B value	B	T=25/50°C	3305	3375	3450	K	

\*4:Biggest internal terminal resistance among arm.

**● Thermal resistance characteristics**

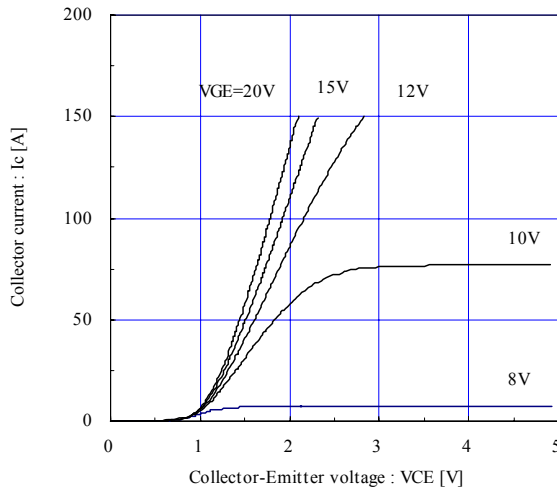
Items	Symbols	Conditions	Characteristics			Unit
			Min.	Typ.	Max.	
Thermal resistance	R <sub>th(j-c)</sub>	IGBT	-	-	0.32	°C/W
	R <sub>th(j-c)</sub>	FWD	-	-	0.73	°C/W
Contact Thermal resistance	R <sub>th(c-f)</sub> *5	With thermal compound	-	0.05	-	°C/W

\*5: This is the value which is defined mounting on the additional cooling fin with thermal compound

Characteristics (Representative)

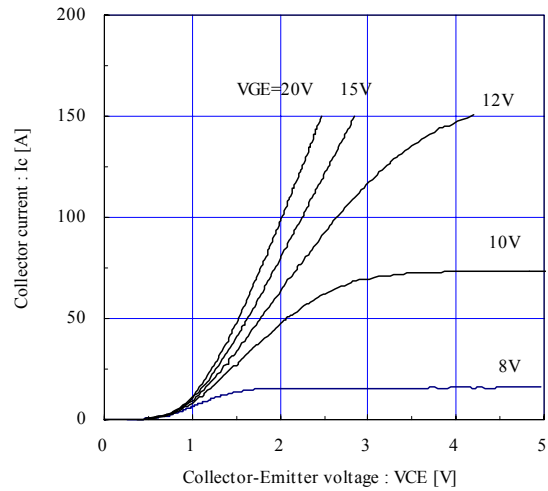
Collector current vs. Collector-Emitter voltage (typ.)

T<sub>j</sub> = 25°C / chip



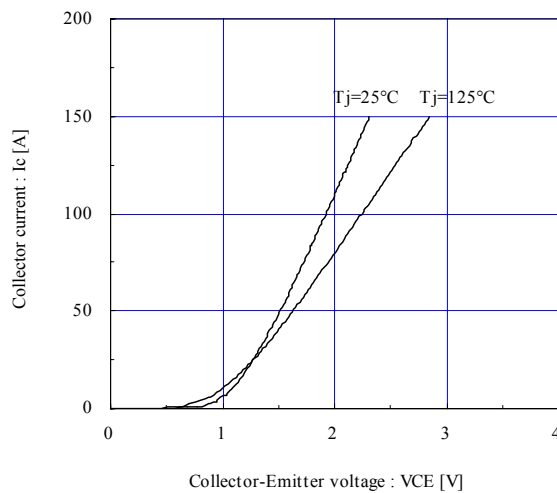
Collector current vs. Collector-Emitter voltage (typ.)

T<sub>j</sub> = 125°C / chip



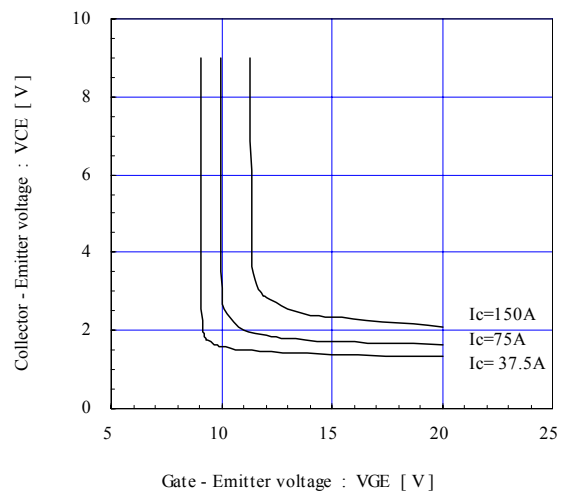
Collector current vs. Collector-Emitter voltage (typ.)

VGE = 15V / chip



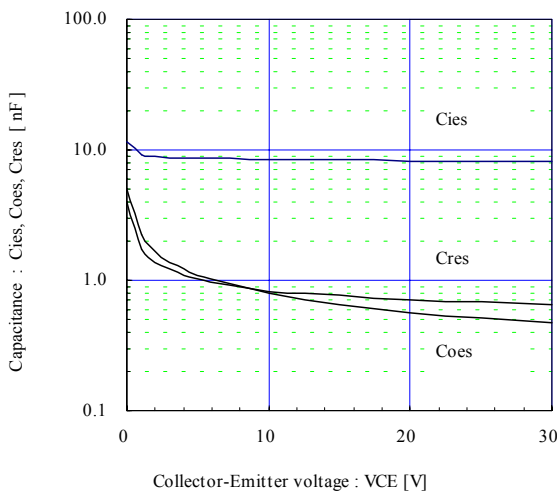
Collector-Emitter voltage vs. Gate-Emitter voltage (typ.)

T<sub>j</sub> = 25°C / chip



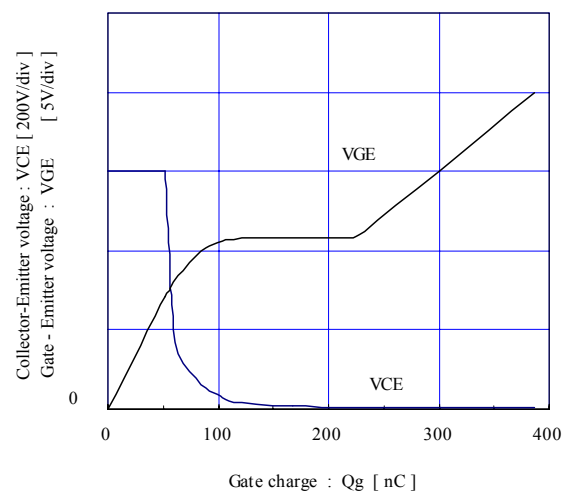
Capacitance vs. Collector-Emitter voltage (typ.)

VGE = 0V, f = 1MHz, T<sub>j</sub> = 25°C

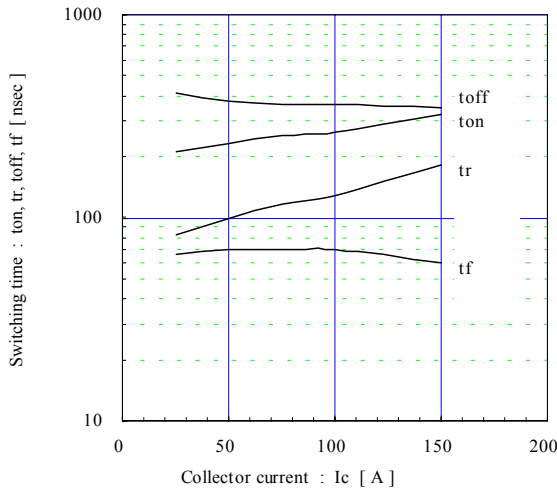


Dynamic Gate charge (typ.)

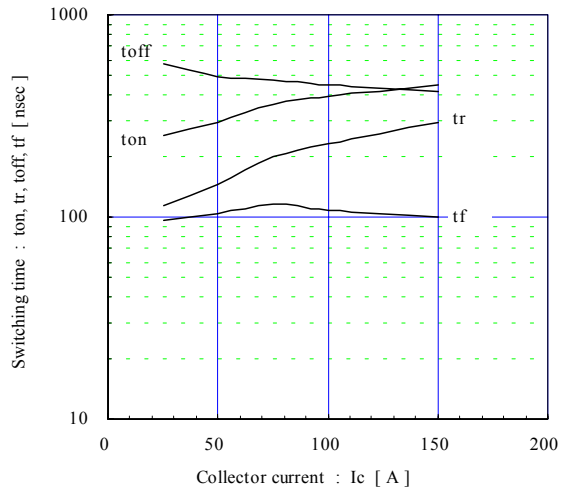
V<sub>ce</sub> = 600V, I<sub>c</sub> = 75A, T<sub>j</sub> = 25°C



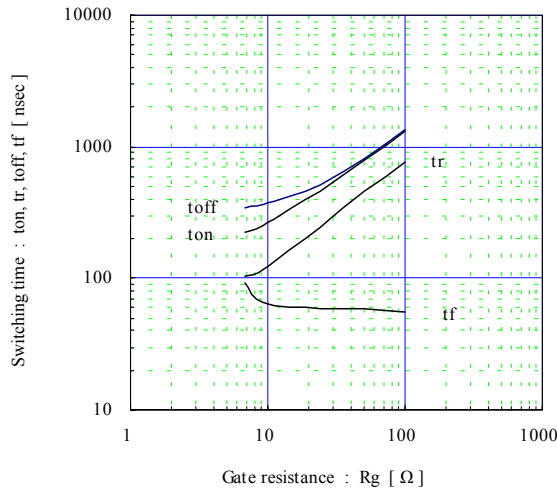
Switching time vs. Collector current (typ.)  
 $V_{cc}=600V, V_{GE}=\pm 15V, R_g=9.1\Omega, T_j=25^\circ C$



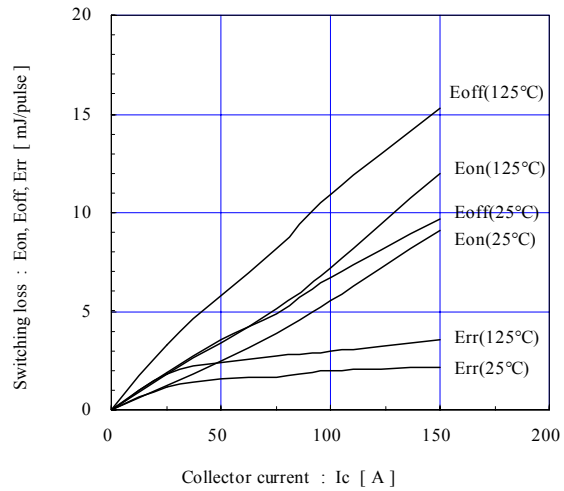
Switching time vs. Collector current (typ.)  
 $V_{cc}=600V, V_{GE}=\pm 15V, R_g=9.1\Omega, T_j=125^\circ C$



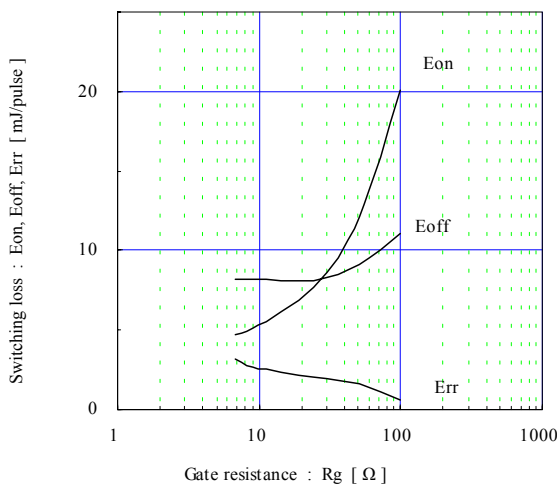
Switching time vs. Gate resistance (typ.)  
 $V_{cc}=600V, I_c=75A, V_{GE}=\pm 15V, T_j=25^\circ C$



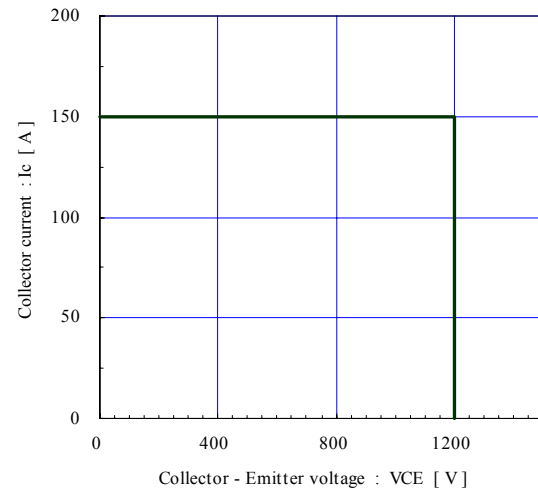
Switching loss vs. Collector current (typ.)  
 $V_{cc}=600V, V_{GE}=\pm 15V, R_g=9.1\Omega$



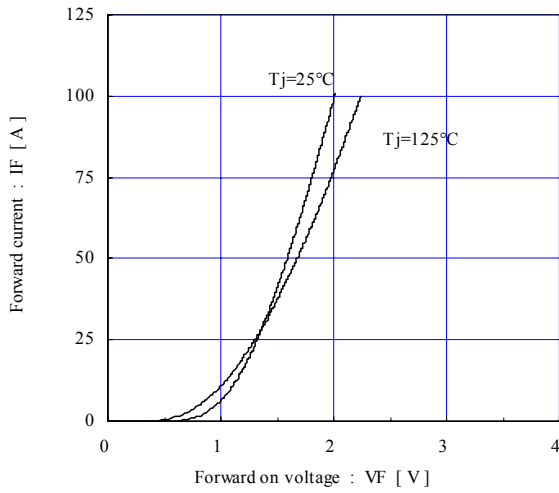
Switching loss vs. Gate resistance (typ.)  
 $V_{cc}=600V, I_c=75A, V_{GE}=\pm 15V, T_j=125^\circ C$



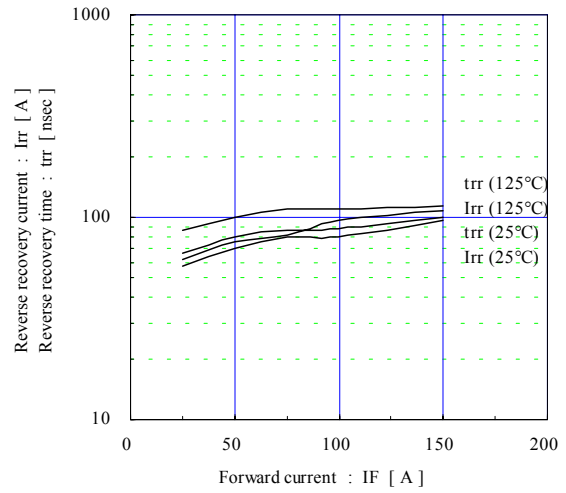
Reverse bias safe operating area (max.)  
 $+V_{GE}=15V, -V_{GE} \leq 15V, R_g \geq 9.1\Omega, T_j \leq 125^\circ C$



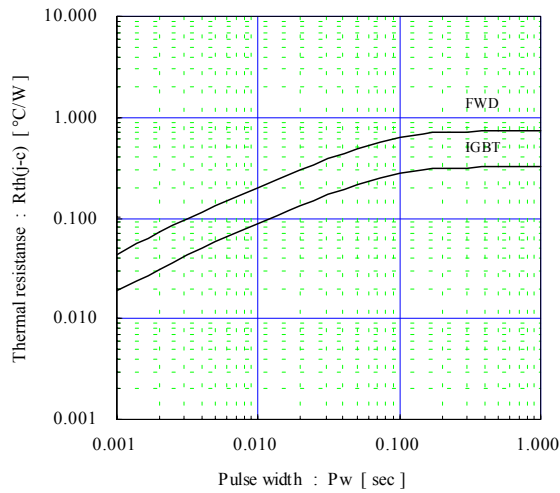
Forward current vs. Forward on voltage (typ.)  
chip



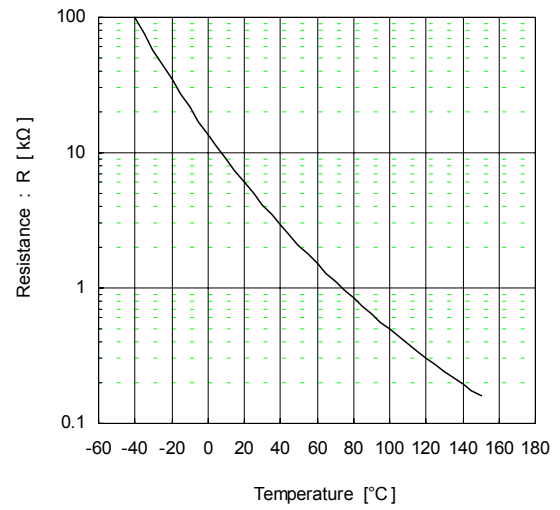
Reverse recovery characteristics (typ.)  
 $V_{ce}=600\text{V}$ ,  $V_{GE}=\pm 15\text{V}$ ,  $R_g=9.1\Omega$



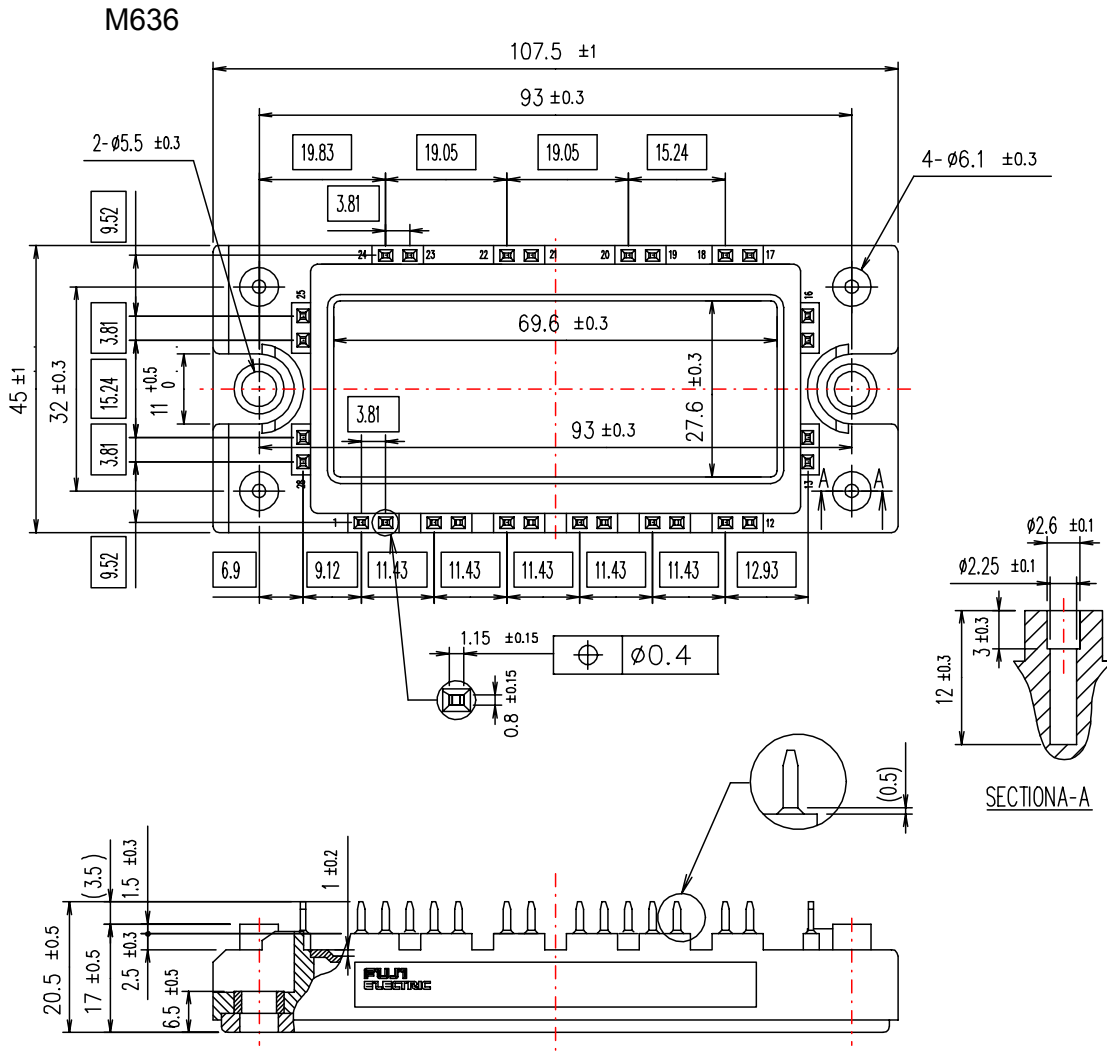
Transient thermal resistance (max.)



Temperature characteristic (typ.)



■ Outline Drawings, mm



□ shows theoretical dimension.  
 ( ) shows reference dimension.

■ Equivalent Circuit Schematic

